

## General Description

The GreenMOS® high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS® Generic series is optimized for extreme switching performance to minimize switching loss. It is tailored for high power density applications to meet the highest efficiency standards.

## Features

- Low  $R_{DS(on)}$  & FOM
- Extremely low switching loss
- Excellent stability and uniformity



## Applications

- PC power
- LED lighting
- Telecom power
- Server power
- EV Charger
- Solar/UPS

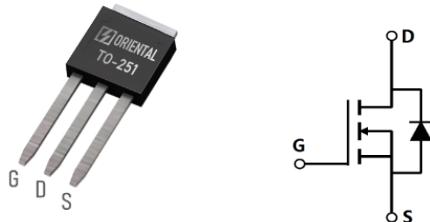
## Key Performance Parameters

| Parameter                      | Value | Unit |
|--------------------------------|-------|------|
| $V_{DS, min} @ T_{j(max)}$     | 650   | V    |
| $I_D, pulse$                   | 33    | A    |
| $R_{DS(ON), max} @ V_{GS}=10V$ | 380   | mΩ   |
| $Q_g$                          | 13    | nC   |

## Marking Information

| Product Name | Package | Marking    |
|--------------|---------|------------|
| OSG60R380AF  | TO251   | OSG60R380A |

## Package & Pin Information



**Absolute Maximum Ratings** at  $T_j=25^\circ\text{C}$  unless otherwise noted

| Parameter   | Symbol               | Value      | Unit             |
|---|----------------------|------------|------------------|
| Drain-source voltage  | $V_{DS}$             | 600        | V                |
| Gate-source voltage   | $V_{GS}$             | $\pm 30$   | V                |
| Continuous drain current <sup>1)</sup> , $T_C=25\text{ }^\circ\text{C}$         | $I_D$                | 11         | A                |
| Continuous drain current <sup>1)</sup> , $T_C=100\text{ }^\circ\text{C}$        |                      | 7          |                  |
| Pulsed drain current <sup>2)</sup> , $T_C=25\text{ }^\circ\text{C}$             | $I_{D,\text{pulse}}$ | 33         | A                |
| Continuous diode forward current <sup>1)</sup> , $T_C=25\text{ }^\circ\text{C}$ | $I_S$                | 11         | A                |
| Diode pulsed current <sup>2)</sup> , $T_C=25\text{ }^\circ\text{C}$             | $I_{S,\text{pulse}}$ | 33         | A                |
| Power dissipation <sup>3)</sup> $T_C=25\text{ }^\circ\text{C}$                  | $P_D$                | 83         | W                |
| Single pulsed avalanche energy <sup>5)</sup>                                    | $E_{AS}$             | 272        | mJ               |
| MOSFET dv/dt ruggedness, $V_{DS}=0\text{...}480\text{ V}$                       | dv/dt                | 50         | V/ns             |
| Reverse diode dv/dt, $V_{DS}=0\text{...}480\text{ V}$ , $I_{SD}\leq I_D$        | dv/dt                | 15         | V/ns             |
| Operation and storage temperature   | $T_{stg}, T_j$       | -55 to 150 | $^\circ\text{C}$ |

**Thermal Characteristics**

| Parameter  | Symbol          | Value | Unit               |
|--|-----------------|-------|--------------------|
| Thermal resistance, junction-case                  | $R_{\theta JC}$ | 1.5   | $^\circ\text{C/W}$ |
| Thermal resistance, junction-ambient <sup>4)</sup> | $R_{\theta JA}$ | 62    | $^\circ\text{C/W}$ |

**Electrical Characteristics** at  $T_j=25^\circ\text{C}$  unless otherwise specified

| Parameter                        | Symbol              | Min. | Typ. | Max. | Unit          | Test condition   |
|----------------------------------|---------------------|------|------|------|---------------|--|
| Drain-source breakdown voltage   | $BV_{DSS}$          | 600  |      |      | V             | $V_{GS}=0\text{ V}$ , $I_D=250\text{ }\mu\text{A}$                                   |
|                                  |                     | 650  | 716  |      |               | $V_{GS}=0\text{ V}$ , $I_D=250\text{ }\mu\text{A}$ , $T_j=150\text{ }^\circ\text{C}$ |
| Gate threshold voltage           | $V_{GS(\text{th})}$ | 2.0  |      | 4.0  | V             | $V_{DS}=V_{GS}$ , $I_D=250\text{ }\mu\text{A}$                                       |
| Drain-source on-state resistance | $R_{DS(\text{ON})}$ |      | 0.33 | 0.38 | $\Omega$      | $V_{GS}=10\text{ V}$ , $I_D=5.5\text{ A}$  |
|                                  |                     |      | 0.83 |      |               | $V_{GS}=10\text{ V}$ , $I_D=5.5\text{ A}$ , $T_j=150\text{ }^\circ\text{C}$          |
| Gate-source leakage current      | $I_{GSS}$           |      |      | 100  | nA            | $V_{GS}=30\text{ V}$   |
|                                  |                     |      |      | -100 |               | $V_{GS}=-30\text{ V}$  |
| Drain-source leakage current     | $I_{DSS}$           |      |      | 1    | $\mu\text{A}$ | $V_{DS}=600\text{ V}$ , $V_{GS}=0\text{ V}$  |

### Dynamic Characteristics

| Parameter                    | Symbol              | Min. | Typ. | Max. | Unit | Test condition   |
|------------------------------|---------------------|------|------|------|------|--|
| Input capacitance            | C <sub>iss</sub>    |      | 690  |      | pF   | V <sub>GS</sub> =0 V,<br>V <sub>DS</sub> =50 V,<br>f=1 MHz   |
| Output capacitance           | C <sub>oss</sub>    |      | 57   |      | pF   |  |
| Reverse transfer capacitance | C <sub>rss</sub>    |      | 2.47 |      | pF   |  |
| Turn-on delay time           | t <sub>d(on)</sub>  |      | 26   |      | ns   | V <sub>GS</sub> =10 V,<br>V <sub>DS</sub> =380 V,<br>R <sub>G</sub> =25 Ω,<br>I <sub>D</sub> =11 A |
| Rise time                    | t <sub>r</sub>      |      | 28.3 |      | ns   |  |
| Turn-off delay time          | t <sub>d(off)</sub> |      | 34   |      | ns   |  |
| Fall time                    | t <sub>f</sub>      |      | 33.2 |      | ns   |  |

### Gate Charge Characteristics

| Parameter            | Symbol               | Min. | Typ. | Max. | Unit | Test condition  |
|----------------------|----------------------|------|------|------|------|---|
| Total gate charge    | Q <sub>g</sub>       |      | 13   |      | nC   | V <sub>GS</sub> =11 V,<br>V <sub>DS</sub> =480 V,<br>I <sub>D</sub> =10 A |
| Gate-source charge   | Q <sub>gs</sub>      |      | 3.6  |      | nC   |   |
| Gate-drain charge    | Q <sub>gd</sub>      |      | 5.6  |      | nC   |   |
| Gate plateau voltage | V <sub>plateau</sub> |      | 5.6  |      | V    |   |

### Body Diode Characteristics

| Parameter                     | Symbol           | Min. | Typ. | Max. | Unit | Test condition  |
|-------------------------------|------------------|------|------|------|------|---|
| Diode forward voltage         | V <sub>SD</sub>  |      |      | 1.3  | V    | I <sub>S</sub> =11 A,<br>V <sub>GS</sub> =0 V                     |
| Reverse recovery time         | t <sub>rr</sub>  |      | 266  |      | ns   | V <sub>R</sub> =400 V,<br>I <sub>S</sub> =11 A,<br>di/dt=100 A/μs |
| Reverse recovery charge       | Q <sub>rr</sub>  |      | 2.8  |      | μC   |   |
| Peak reverse recovery current | I <sub>rrm</sub> |      | 19.6 |      | A    |   |

### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R<sub>θJA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>a</sub>=25 °C.
- 5) V<sub>DD</sub>=50 V, V<sub>GS</sub>=10 V, L=10.8 mH, starting T<sub>j</sub>=25 °C.

### Electrical Characteristics Diagrams

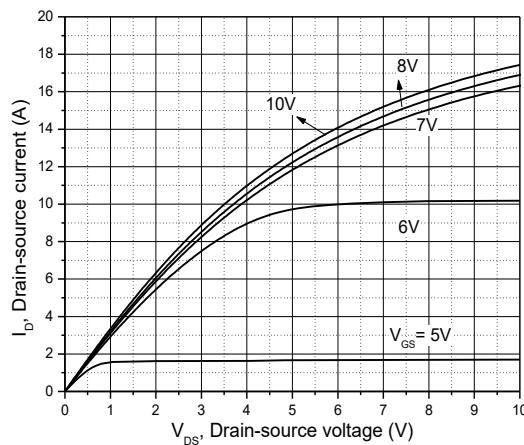


Figure 1. Typ. output characteristics

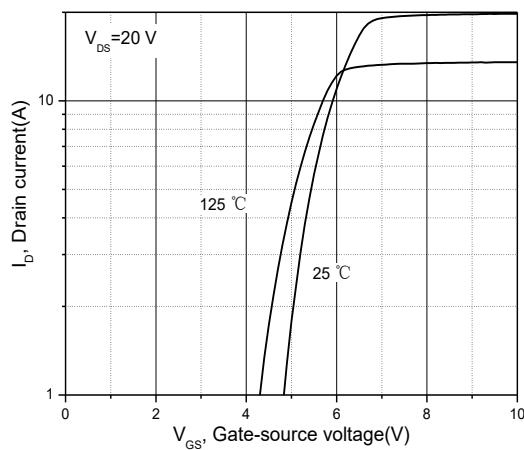


Figure 2. Typ. transfer characteristics

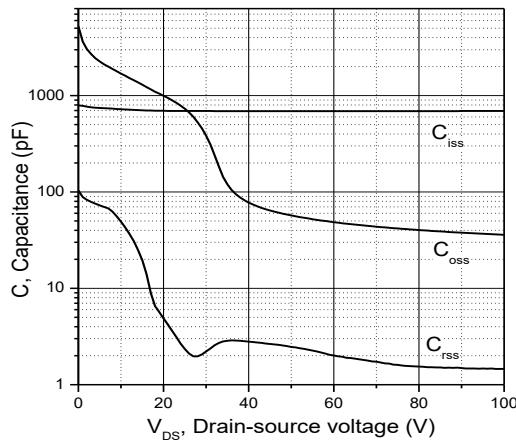


Figure 3. Typ. capacitances

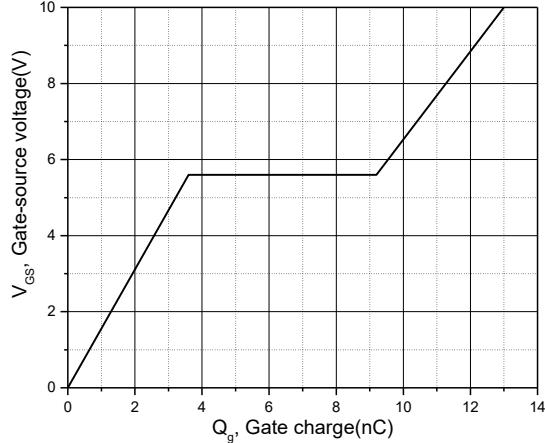


Figure 4. Typ. gate charge

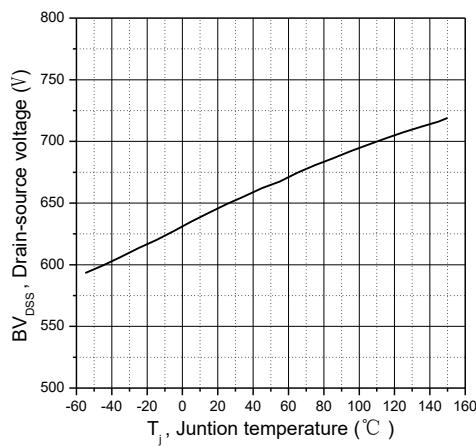


Figure 5. Drain-source breakdown voltage

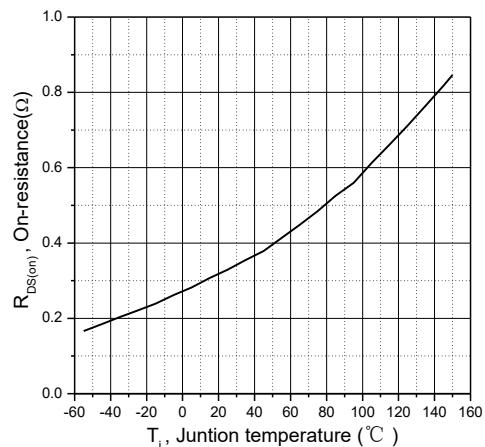
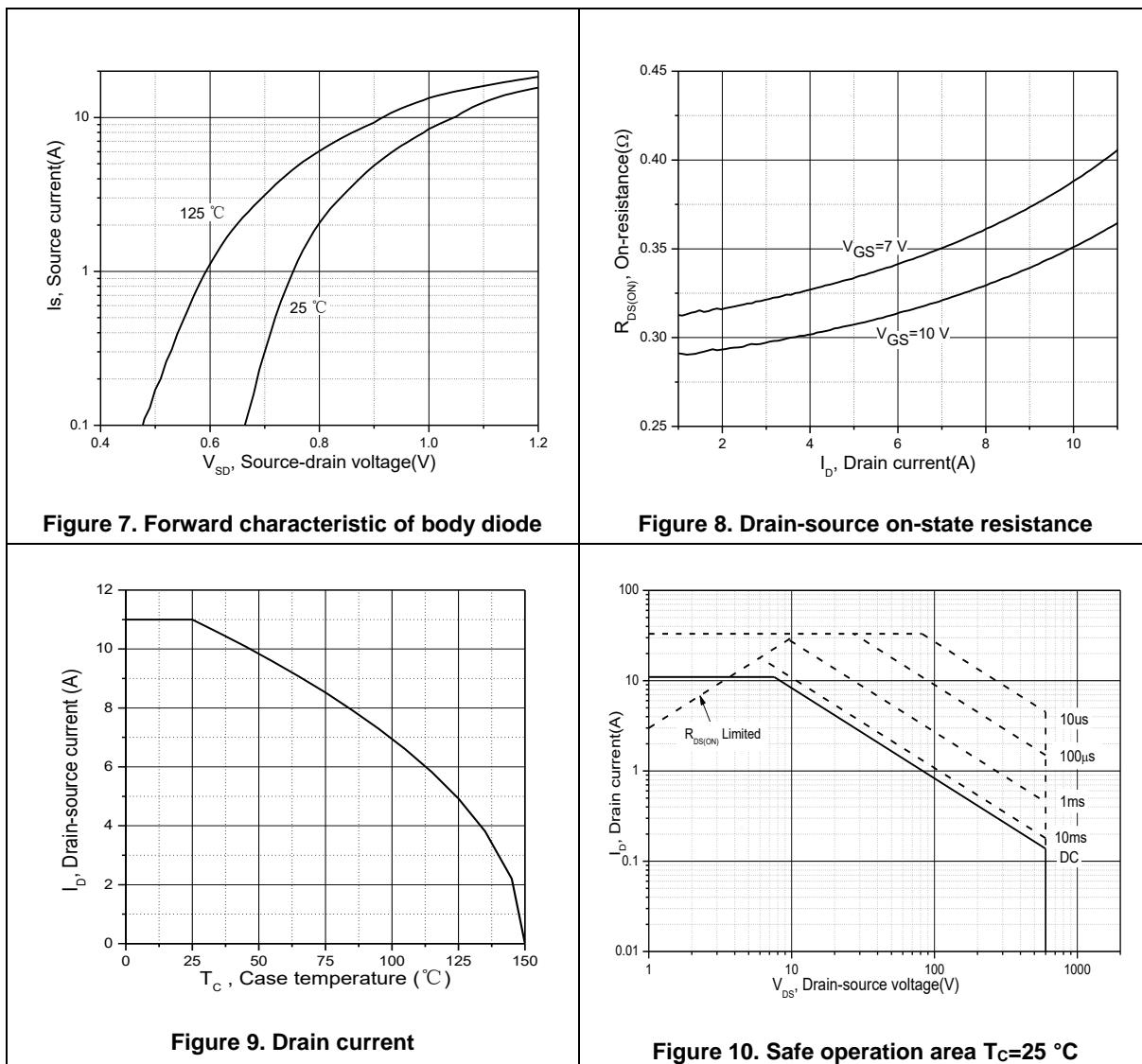
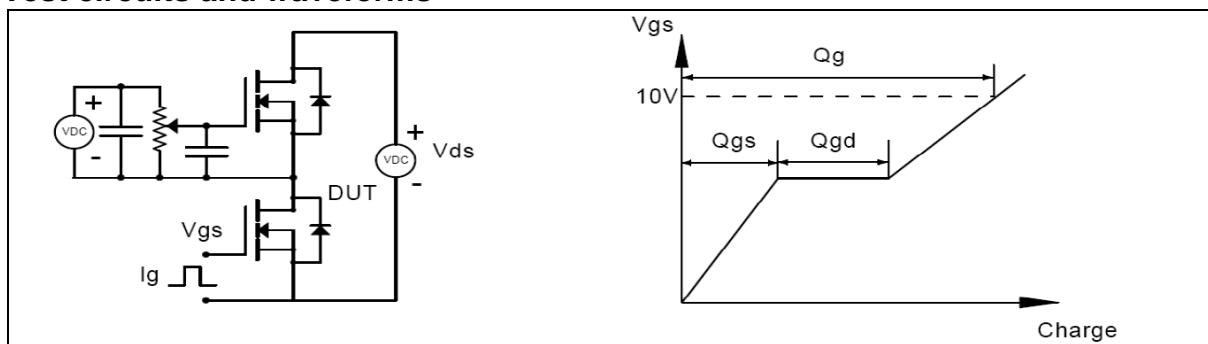
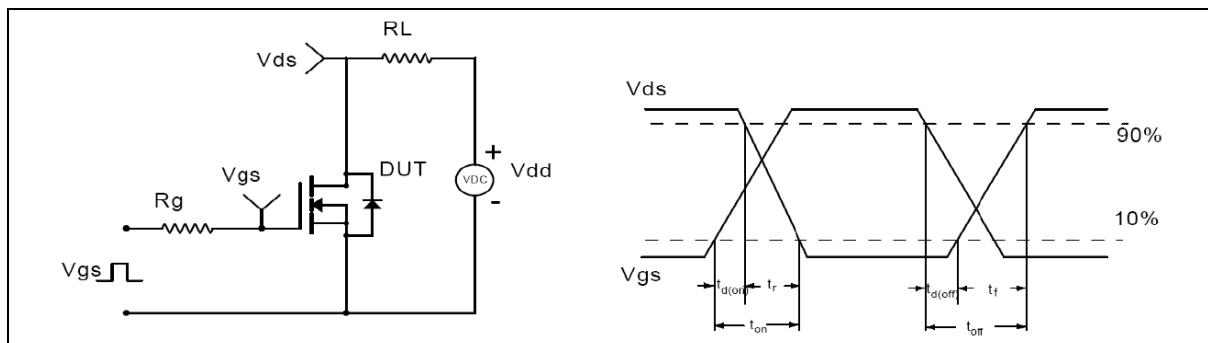
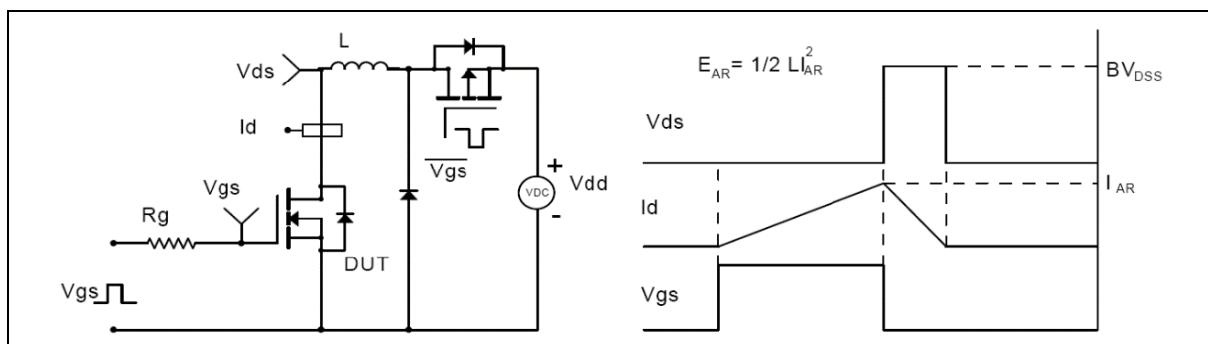
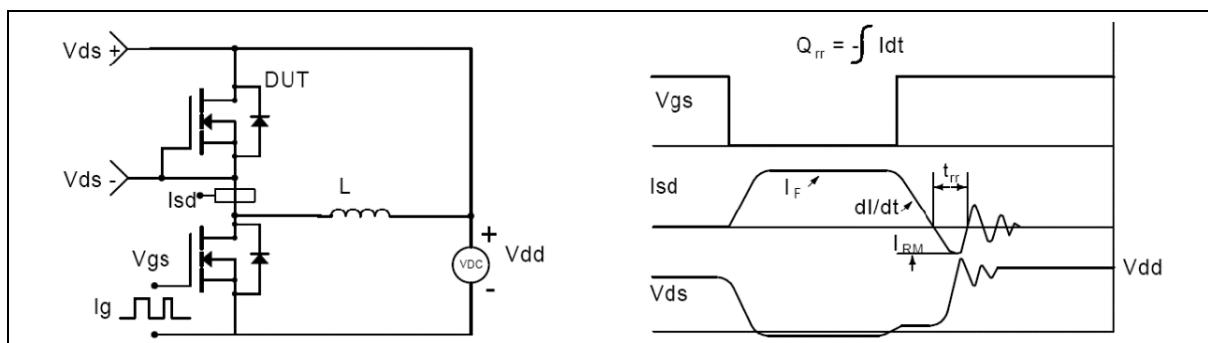
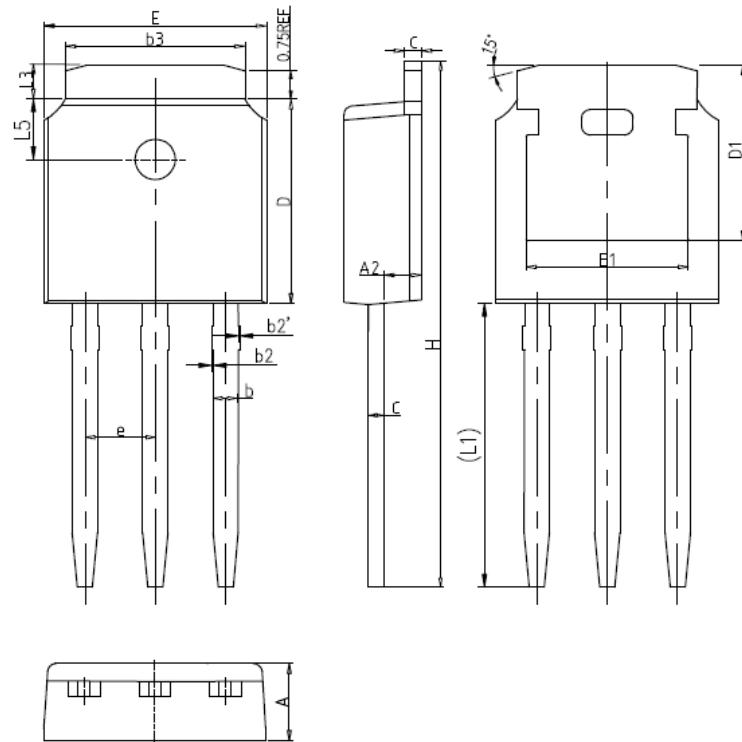


Figure 6. Drain-source on-state resistance



**Test circuits and waveforms**

**Figure 1. Gate charge test circuit & waveform**

**Figure 2. Switching time test circuit & waveforms**

**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**

**Figure 4. Diode reverse recovery test circuit & waveforms**

## Package Information



| Symbol | mm       |       |       |
|--------|----------|-------|-------|
|        | Min      | Nom   | Max   |
| A      | 2.20     | 2.30  | 2.40  |
| A2     | 0.97     | 1.07  | 1.17  |
| b      | 0.68     | 0.78  | 0.90  |
| b2     | 0.00     | 0.04  | 0.10  |
| b2'    | 0.00     | 0.04  | 0.10  |
| b3     | 5.20     | 5.33  | 5.50  |
| c      | 0.43     | 0.53  | 0.63  |
| D      | 5.98     | 6.10  | 6.22  |
| D1     | 5.30REF  |       |       |
| E      | 6.40     | 6.60  | 6.80  |
| E1     | 4.63     | -     | -     |
| e      | 2.286BSC |       |       |
| H      | 16.22    | 16.52 | 16.82 |
| L1     | 9.15     | 9.40  | 9.65  |
| L3     | 0.88     | 1.02  | 1.28  |
| L5     | 1.65     | 1.80  | 1.95  |

Version1: TO251-C package outline dimension

## Ordering Information

| Package Type | Units/ Tube | Tubes / Inner Box | Units/ Inner Box | Inner Boxes/ Carton Box | Units/ Carton Box |
|--------------|-------------|-------------------|------------------|-------------------------|-------------------|
| TO251-C      | 75          | 66                | 4950             | 6                       | 29700             |

## Product Information

| Product     | Package | Pb Free | RoHS | Halogen Free |
|-------------|---------|---------|------|--------------|
| OSG60R380AF | TO251   | yes     | yes  | yes          |

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